Schedule of Accreditation

issued by

United Kingdom Accreditation Service

2 Pine Trees, Chertsey Lane, Staines-upon-Thames, TW18 3HR, UK



DETAIL OF ACCREDITATION

| Materials/Products tested | Type of test/Properties measured/Range of measurement | Standard specifications/ Equipment/Techniques used |
|--|---|---|
| ENGINEERING MATERIAL, MACHINERY, STRUCTURES AND PRODUCTS | Elemental Analysis | |
| Electronics/Semiconductors | | |
| Electrical, Electronic, and Electromechanical (EEE) parts to mitigate the risks of receiving or using Suspect/Counterfeit (SC) EEE parts | Suspect/Counterfeit Test Evaluation Methods | Aerospace Standard SAE AS6171:2018 tests methods. |
| | | For counterfeit defect and counterfeit type coverages by a sequence of tests, using a Model assignment, Moderate risk model 2 |
| | AS6171/2 Detection by External Visual Inspection (EVI), Remarking and Resurfacing, and Surface Texture | Visual and high magnification inspection to detect recycled or counterfeit products (i.e., removed from boards or assemblies and reworked by straightening of leads, retinning the leads, removal of the original marking and remarking, and/or blacktopping the component to hide evidence of the remarking and counterfeiting). Excluding AS 6171/2 METHOD F (SEM) |
| | AS6171/3: Detection by X-ray Fluorescence (XRF) test methods | Analysis of elements Pb, Cu, Zn, Ni, Ag Sn The plating layer thicknesses, presence of barrier materials, and the base material from some expected material compositions. |



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Retronix Ltd

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Accredited to ISO/IEC 17025:2017

Testing performed at main address only

| Materials/Products tested | Type of test/Properties measured/Range of measurement | Standard specifications/ Equipment/Techniques used | |
|---|---|---|--|
| ENGINEERING MATERIAL, MACHINERY, STRUCTURES AND PRODUCTS (cont'd) | Elemental Analysis (cont'd) | | |
| Electronics/Semiconductors (cont'd) | | | |
| Electrical, Electronic, and Electromechanical (EEE) parts to mitigate the risks of receiving or using Suspect/Counterfeit (SC) EEE parts (cont'd) | AS6171/4: Detection by Delid/Decapsulation Physical Analysis (DDPA) using in house test methods RTS-TL-SOP-005 | To verify that die attributes are consistent with the known manufacturer of the device. | |
| | AS6171/5: Detection by Radiological (X-ray) test methods | To examine the internal and external attributes of a part in order to detect deliberate misrepresentation or damage, which could indicate a suspect counterfeit part. Parts are inspected for homogeneity, consistency, and uniformity. | |
| | AS6171/7: Detection by Electrical Test Methods | Electrical testing to verify performance to the published electrical specifications. Covering DC curve trace, Full DC tests at ambient temperatures and over the parts full operating temperature range. Environmental Tests, consisting of Temperature Cycling for active parts. | |
| END | | | |